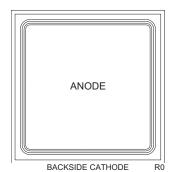


CPD85V-CMPSH1-4L

Schottky Rectifier Die 1.0 Amp, 40 Volt

The CPD85V-CMPSH1-4L is an ultra low V_F silicon Schottky rectifier designed for applications where operational efficiency is a prime requirement.



MECHANICAL SPECIFICATIONS:

39.4 x 39.4 MILS
7.1 MILS
35 x 35 MILS
AI – 30,000Å
Au – 9,000Å
1.97 MILS
5 INCHES
10,900
_

MAXIMUM RATINGS: (TA=25°C)	SYMBOL		UNITS
Continuous Reverse Voltage	V_{R}	40	V
Average Forward Current	IO	1.0	Α
Peak Forward Surge Current, tp=8.3ms	I _{FSM}	20	Α
Operating and Storage Junction Temperature	T _I , T _{eta}	-65 to +150	°C

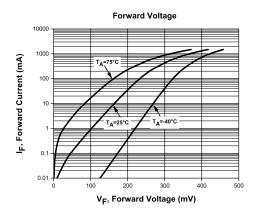
ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted) SYMBOL **TEST CONDITIONS** MIN MAX UNITS I_R $V_R=20V$ 900 μΑ **V_R=30V** 1.5 I_R $\mathsf{m}\mathsf{A}$ BV_R I_R=1.0mA 40 ٧ I_F=100mA mV V_{F} 270 V_{F} I_F=500mA 340 mV V_{F} I_F=1.0A 390 mV V_{F} I_F=1.5A 420 mV V_R=10V, f=1.0MHz 50 СЈ рF

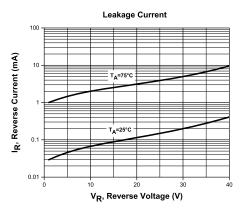
CPD85V-CMPSH1-4L

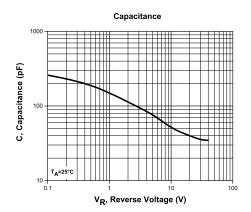
Typical Electrical Characteristics

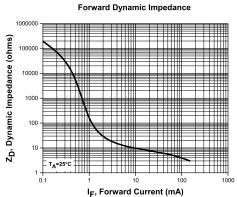


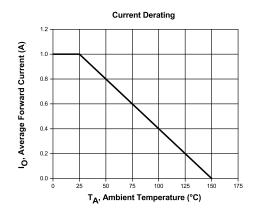
www.centralsemi.com







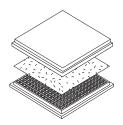




R0 (23-January 2017)

BARE DIE PACKING OPTIONS

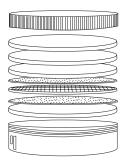




BARE DIE IN TRAY (WAFFLE) PACK

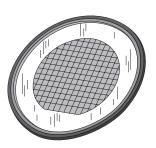
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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